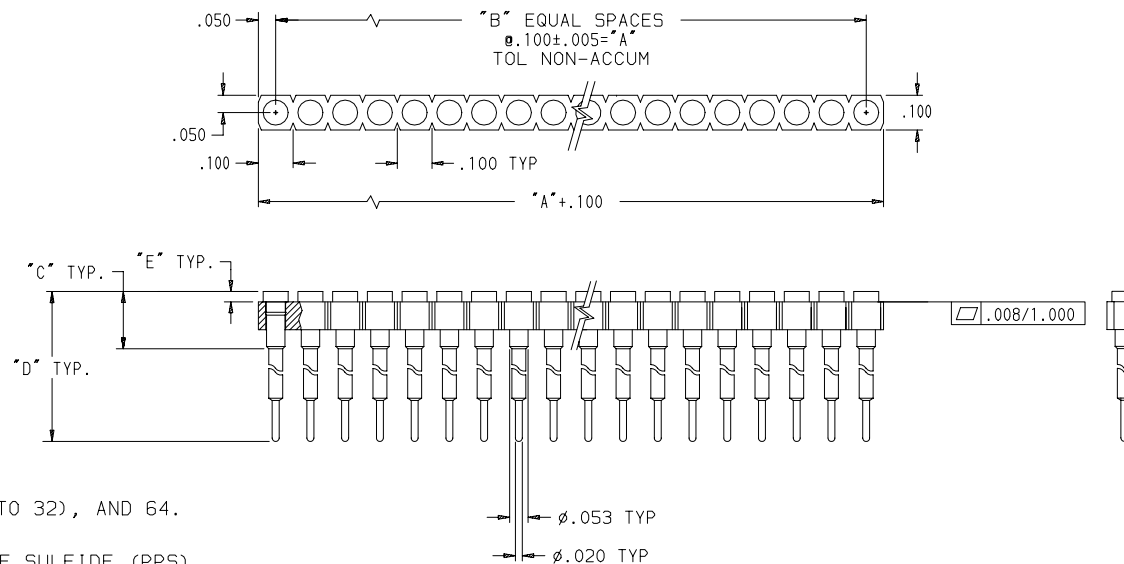


TABLE 1				
PART NUMBER			DIMENSION	
SIP-1 X		[XXX]B(LF)	"A"	"B"
	01		0	0
	02		.100	1
	03		.200	2
	04		.300	3
	05		.400	4
	06		.500	5
	07		.600	6
	08		.700	7
	09		.800	8
	10		.900	9
	11		1.000	10
	12		1.100	11
	13		1.200	12
	14		1.300	13
	15		1.400	14
	16		1.500	15
	17		1.600	16
	18		1.700	17
	19		1.800	18
	20		1.900	19
	21		2.000	20
	22		2.100	21
	23		2.200	22
	24		2.300	23
	25		2.400	24
	26		2.500	25
	27		2.600	26
	28		2.700	27
	29		2.800	28
	30		2.900	29
	31		3.000	30
	32		3.100	31
	64		6.300	63



NOTES:

1. NUMBER OF CONTACTS PER ROW (01 TO 32), AND 64.
2. MATERIAL:
GLASS REINFORCED POLYPHENYLENE SULFIDE (PPS)
RATED UL 94V-0, COLOR BLACK.
3. CONTACT MATERIAL:
OUTER SHELL: BRASS ALLOY 360, 1/2 HARD PER QQ-B-626.
INNER CONTACT: BERYLLIUM COPPER, ALLOY 172 PER QQ-C-533.
4. CONTACT PLATING:
TIN/LEAD OR LEAD-FREE PER MIL-P-81728 TYPE 1,
NICKEL PER QQ-N-290.
GOLD PER MIL-G-45204, TYPE 1, GRADE C.
5. RECOMMENDED PCB THRU HOLE DIA. .026±.003.

6. NOTE RoHS INFORMATION

- The "LF" products meet European Union Directives and other country regulations as described in GS-22-008.
- The housing will withstand exposure to 260°C peak temperature for 20 seconds in a wave solder application with a 1.6mm minimum thick circuit board. See application notes/procedures if they are available.
- Packaging spec: see GS-14-920

LEAD FREE PART NUMBER(see tables)
SIP-1 X [1] - [XXX]BLF

TIN LEAD PART NUMBER (see tables)
SIP-1 X [1] - [XXX]B

American view

 www.fciconnect.com		 ISO 1302		tolerance ISO 406 ISO 1101		projection 		inch 	
Dr	D. WOLFORD	01/10/00	Product family			PGA	size A3	Scale	
Eng	A. VASBINDER	01/10/00	Spec ref			-		1:1	
Chr	A. VASBINDER	01/10/00	Material			SEE NOTES		ECN LS06-0004	
Appr	A. VASBINDER	01/10/00							
title	SINGLE ROW					dwg no	58803		Rev.
	SIP SOCKET								J
catalog no					-	CUSTOMER COPY		sheet # of #	

ltr	ecn no	dr	date
E	V12453	CRG	10/24/0
F	V20347	CRG	02/22/0
G	V05-0037	DAI	04/08/0
H	V05-0424	TAB	05/10/0
J	LS06-0004	LGO	01/05/0
-	-	-	-
-	-	-	-